

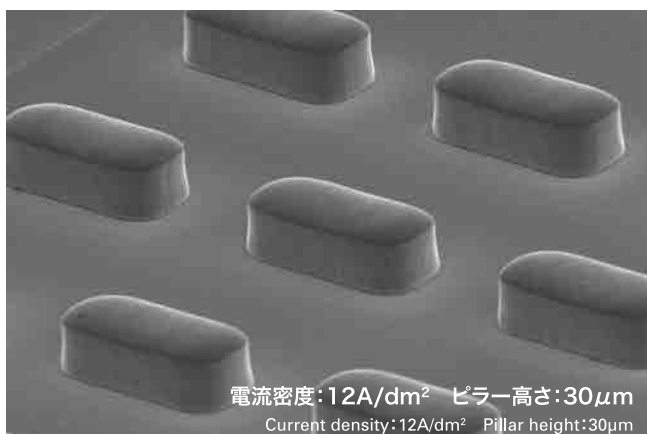
ウエハ用硫酸銅めっき添加剤

トッフルチナCP / トッフルチナSV

Additives for Acid Copper Plating (For Wafer)

TOP LUCINA CP

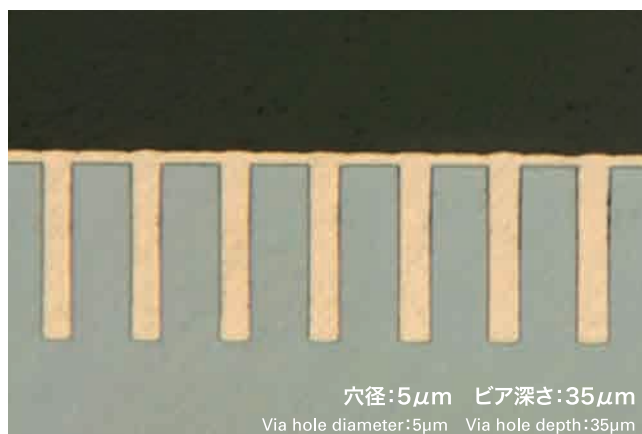
- ▶ 高電流密度対応 (8~12A/dm²)
 - ▶ 良好なパターン形状
 - ▶ 全ての添加剤成分の定量分析が可能
- Applicable to high current density (8 to 12A/dm²)
 - Form uniform, fine patterns
 - Quantitative analysis is possible for all additives



高速めっきが可能で、
銅ピラー等の形成に最適
High-speed plating is possible,
the best for forming copper pillars etc.

TOP LUCINA SV

- ▶ 高アスペクト比ビアのフィリングが可能
 - ▶ 全ての添加剤成分の定量分析が可能
- Realize great via-filling under high aspect ratio
 - Quantitative analysis is possible for all additives



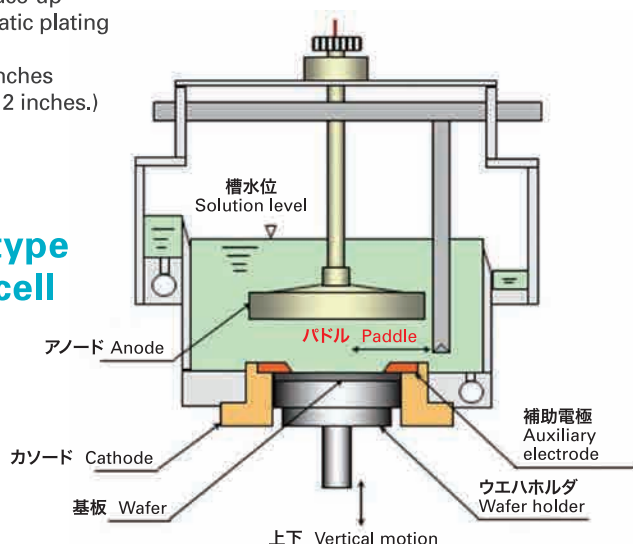
TSV形成用途だけでなく、
高アスペクト比トレンチへの埋め込みにも対応
Can be used for form TSV, also for trench filling under
high aspect ratio

サポート体制 Support system

フェイスアップ式めっき装置で4~8インチの試作試験が可能
(12インチ以上はご相談となります)

We offer trial plating with face-up
paddle model, semi-automatic plating
machine.
Suitable wafer size: 4 to 8 inches
(We need discussion over 12 inches.)

Face-up paddle type plating cell



株式会社東設製
フェイスアップ式半自動めっき装置
Face-up paddle model, semi-automatic
plating machine (Made by Toset Inc.)

